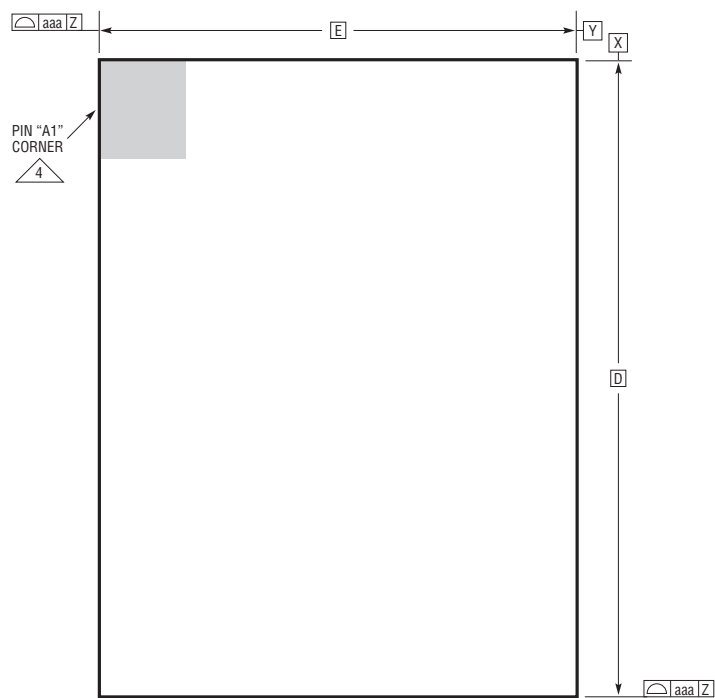
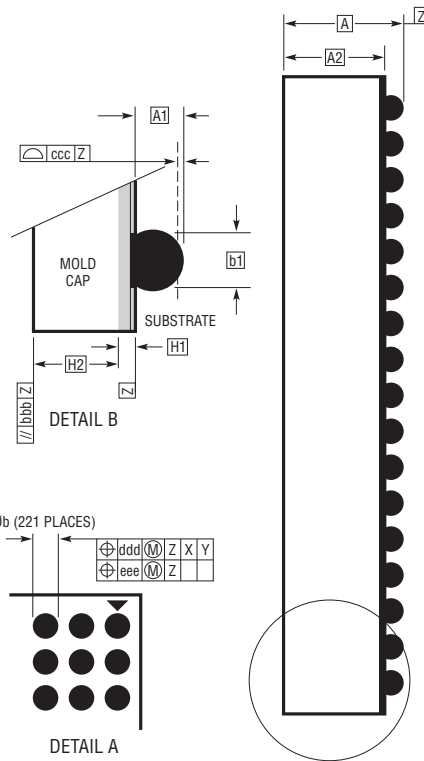


BGA Package
221-Lead (15mm × 11.25mm × 2.82mm)
 (Reference LTC DWG# 05-08-1886 Rev B)

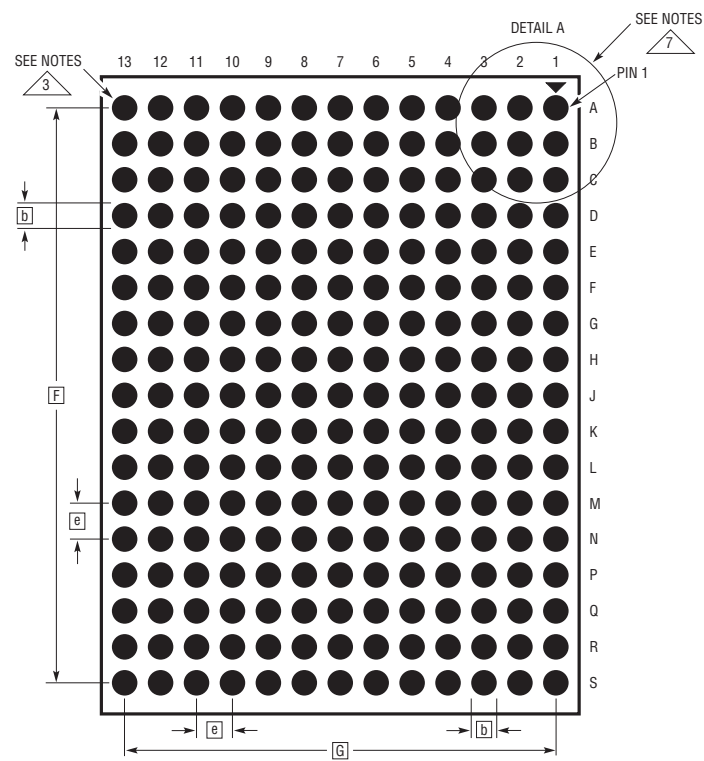


PACKAGE TOP VIEW

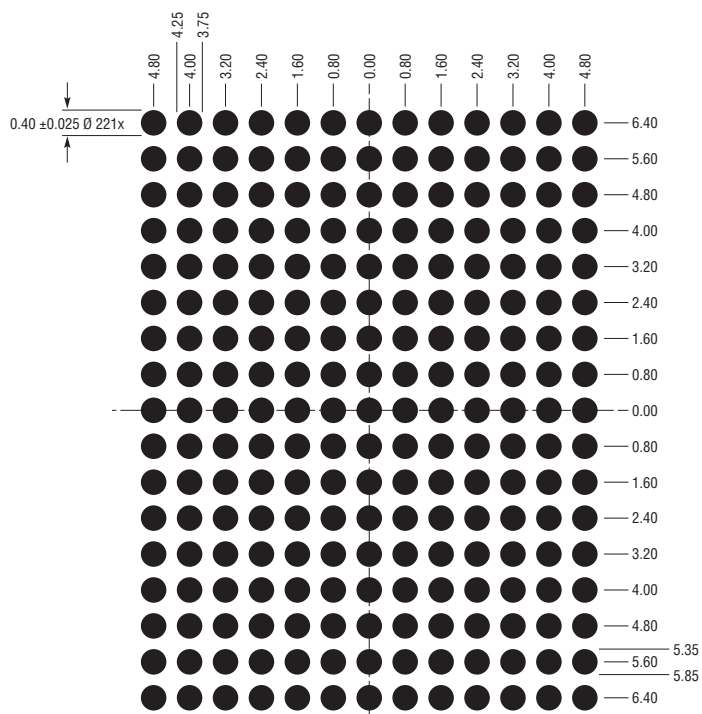


DETAIL A

DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



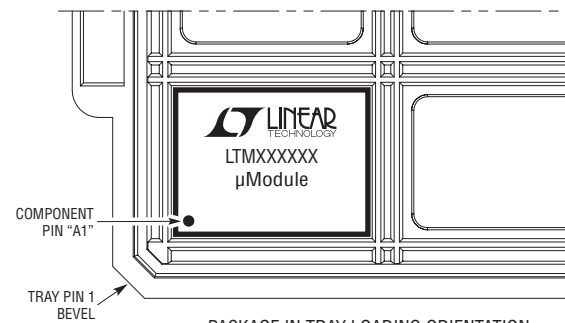
SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.67	2.82	2.97	
A1	0.35	0.40	0.45	
A2	2.32	2.42	2.52	
b	0.45	0.50	0.55	
b1	0.35	0.40	0.45	
D	15.0			
E	11.25			
e	0.80			
F	12.80			
G	9.60			
H1	0.37	0.42	0.47	
H2	1.95	2.00	2.05	
aaa			0.15	
bbb			0.10	
ccc			0.12	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 221

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION